	Junction Temperature	T_j	125	
	Output Power Dissipation	P_O	250	mW
	Power Dissipation Derating (T_a 125)	•P D/	-3.33	mW/
Total Power Dissipation		P_{tot}	350	mW
Isolation Voltage		V_{iso}	5000 '	Vrms
Operating Temperature		T_{opr}	-55~100	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260 8	

NOTE1 (} Œ í u] v µ š U Z X , X A ð ì • ò ì 9

NOTE2 & } Œ í ì • } v •

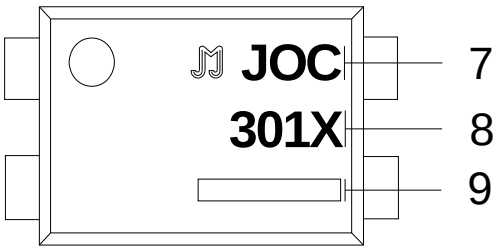
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.24	1.4	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
	Input Capacitance	C_{in}	V=0, f=1kHz	-	10	-	pF
Output	Peak Off-state Current, Either Direction	I_{OFF}	V_{OFF}=250V, I_F=0	-	-	100 "	nA
	Peak On-state Voltage, Either Direction	V_{TM}	I_{TM}=100mA	-	1.8	2.5	V
	Critical Rate of Rise of Off-state voltage	dV/dt	V_{PEAK}=250V, I_F=0	1000 •	-	-	V/μs

Transfer

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



7 : Company Abbr.
8 : Part Number & Rank
9 : Production Information Code

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

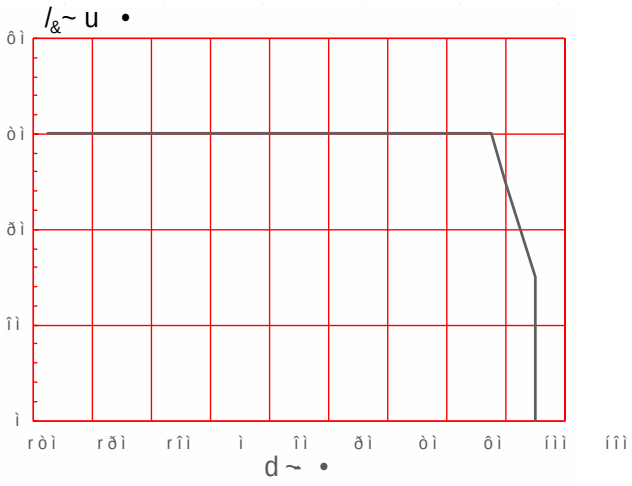


FIG.2: On-state Terminal Current vs. Ambient Temperature

FIG.7: Normalized On-state Terminal Voltage vs. Ambient Temperature

TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

FIG.13: Waveforms of Turn On Time

Fig.14: Test Circuits of dV/dt

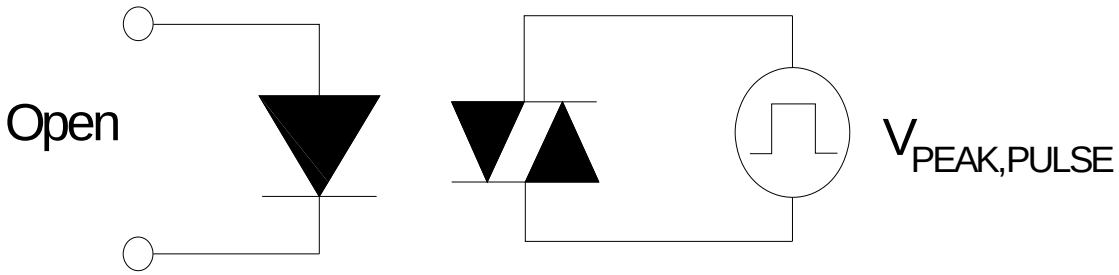
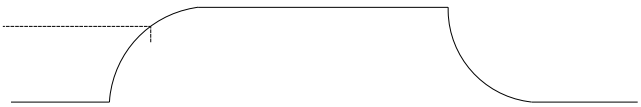
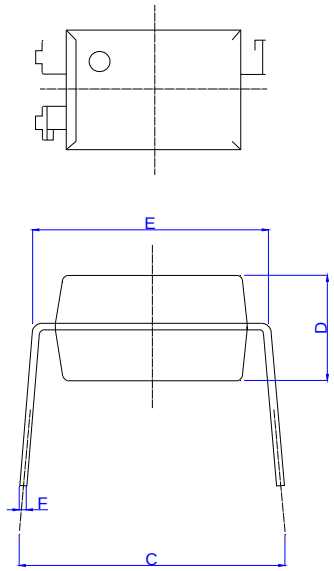


Fig.15: Waveforms of dV/dt



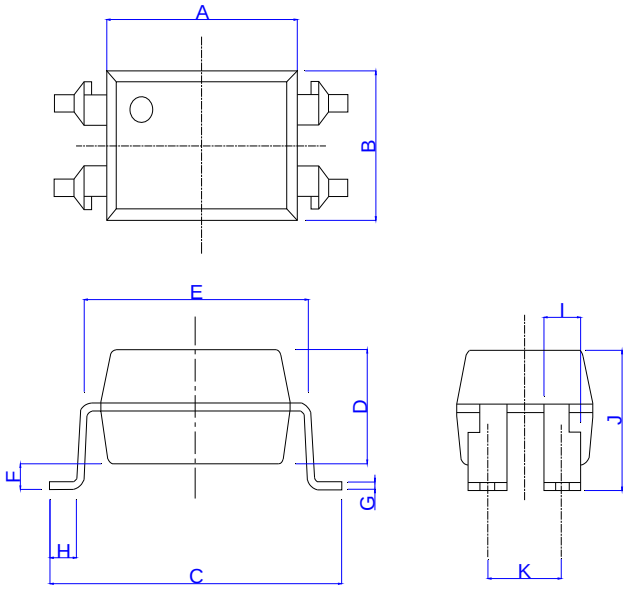
Package Dimension (Unit: mm Å

Standard DIP Type:



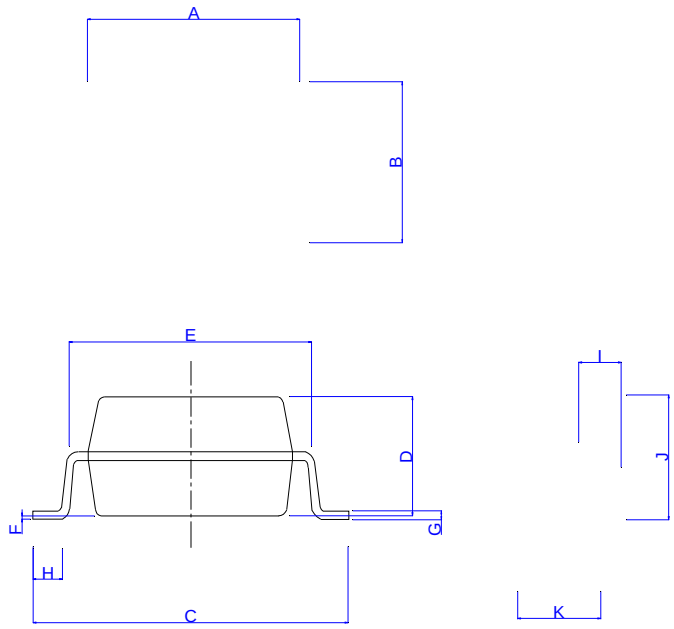
2.80

Option S Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.249		0.265
B	4.38		4.78	0.173		0.189
C	9.85		10.45	0.389		0.413
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.289		0.313
F		0.80			0.032	
G		0.25			0.010	
H		0.80			0.032	
I	1.20		1.40	0.047		0.055
J	4.00		4.60	0.158		0.182
K		2.54			0.100	

Option SL Type:

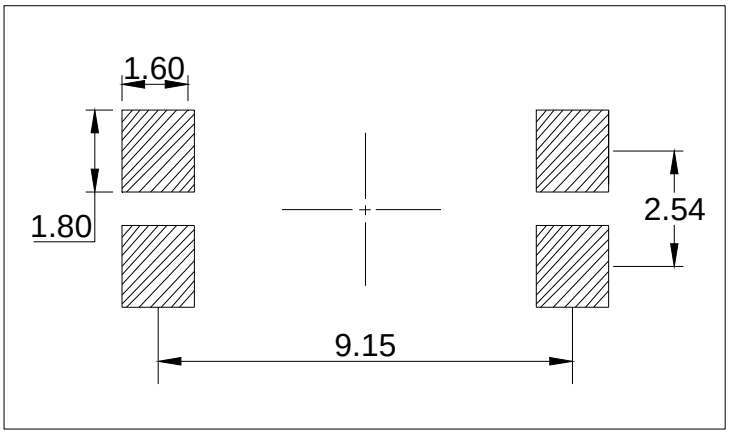


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.249		0.265
B	4.38		4.78	0.274		0.289
C	9.85		10.45	0.389		0.413
E	7.32		7.92	0.289		0.313
G						
I	1.20		1.40	0.047		
K						

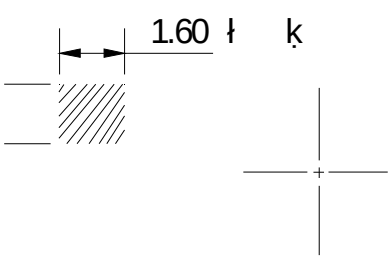
0 1.40 0.

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option S/SL

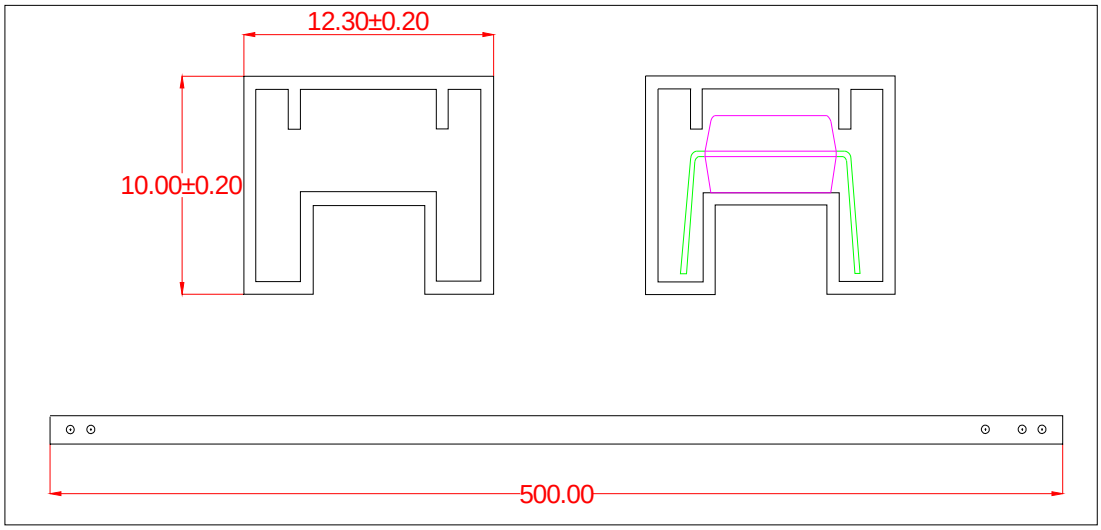


Option SLM

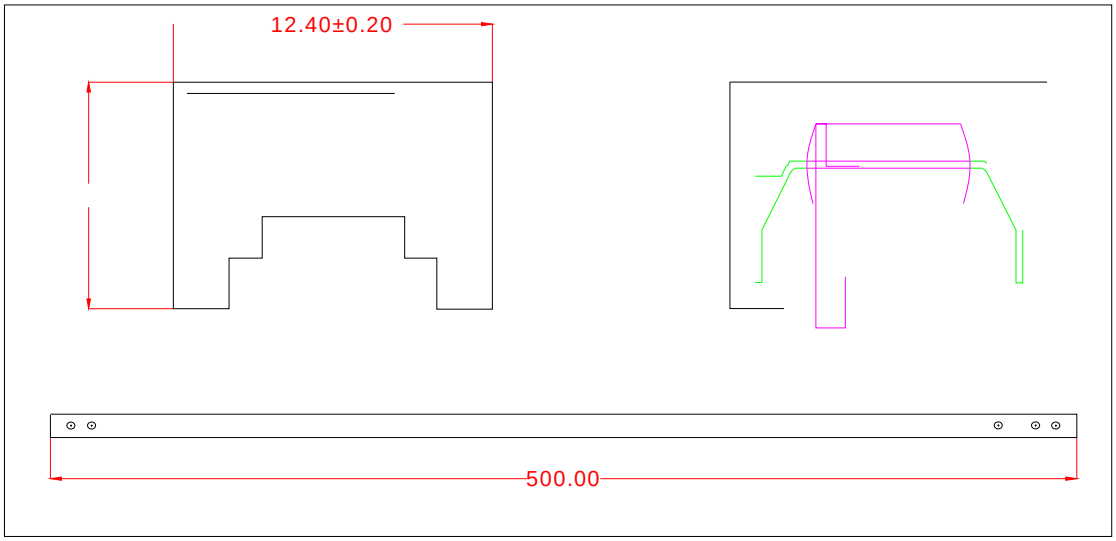


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



Option M



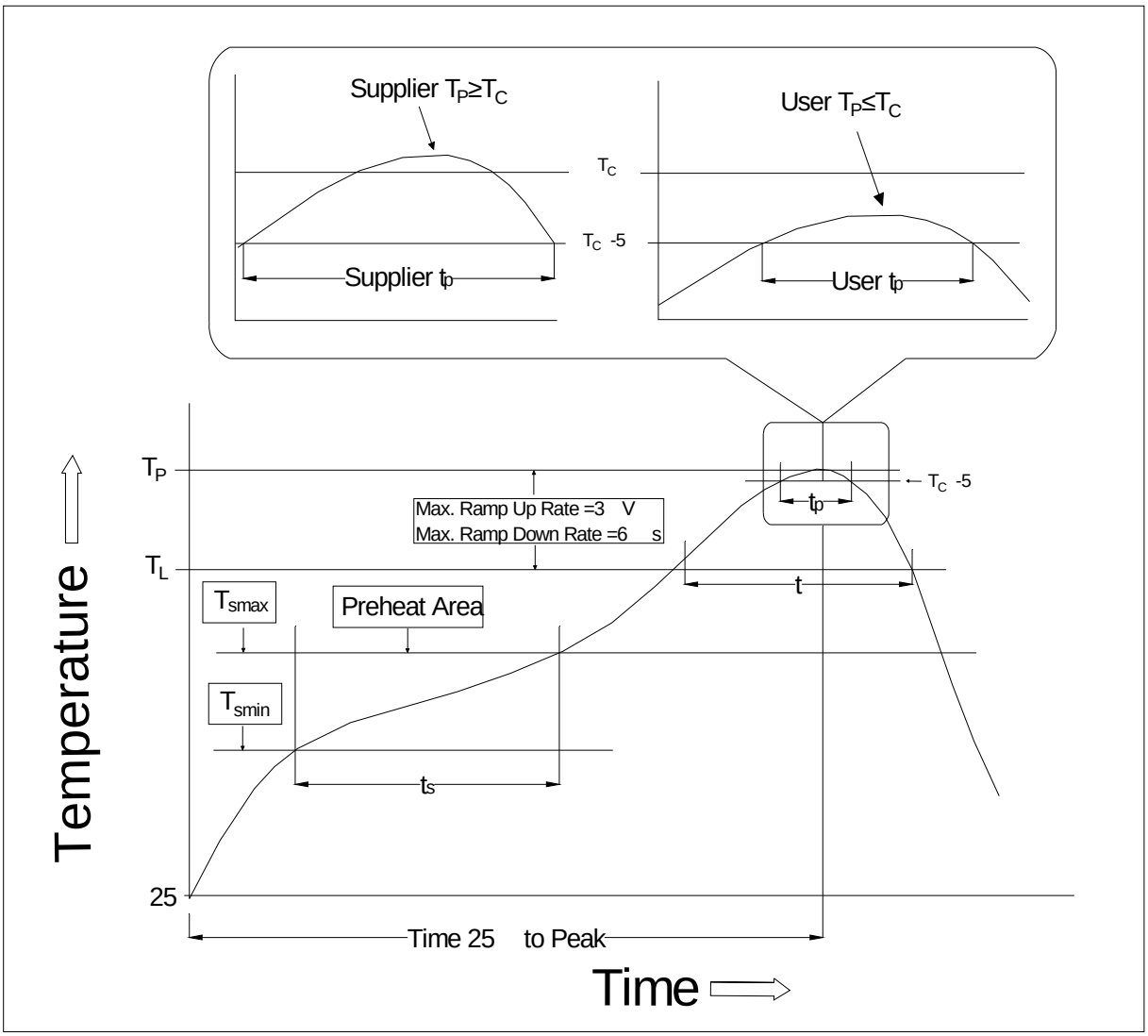
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S



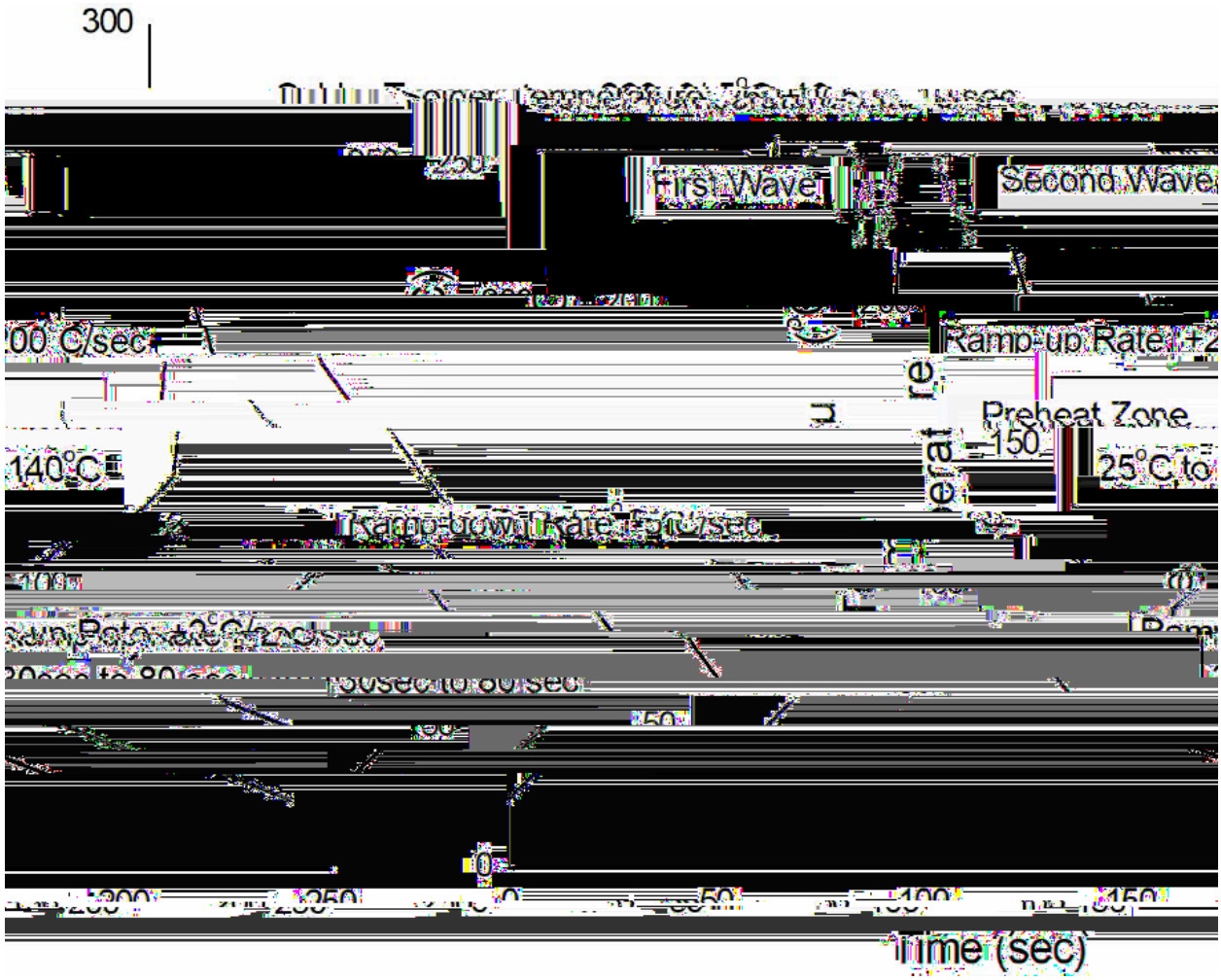
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50			0.059	
P0		4.00			0.157	
P1		8.00			0.315	
P2		2.00			0.079	
E		1.75			0.069	
F		7.50			0.295	
T		0.40			0.016	
W		16.00			0.630	

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 f5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and relia t¢ a Î Mæo